wakefield-vette

ELLIPTICAL FIN HEAT SINK

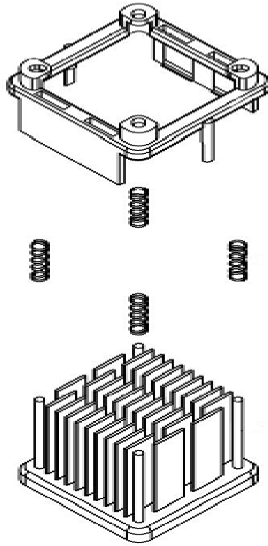
910 Series

Wakefield-Vette's 900 Series Heat Sinks for Chipset can match up to devices from Intel, Broadcom, Xilinx, TI, Motorola and many more.

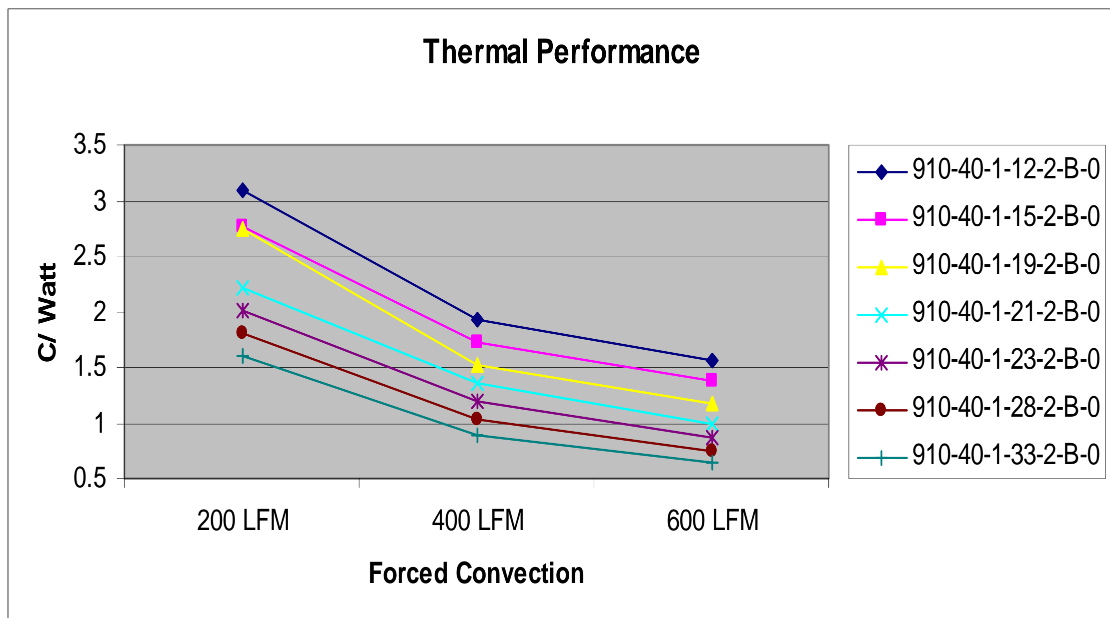
These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, and Cloud Computing Industries.

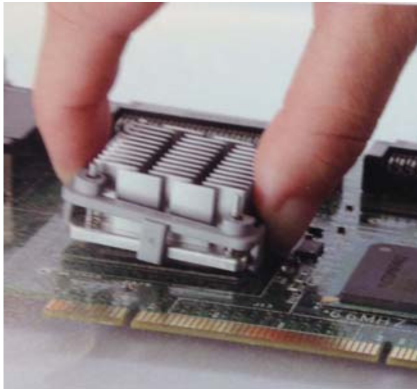
Material: AL 6063

Finish: Black Anodize



PART #	HEIGHT (mm)	CHIP SIZE (mm)	NATURAL CONVECTION	FORCED CONVECTION (C/W)		
				200 LFM	400 LFM	600 LFM
910-40-1-12-2-B-0	12	40	9.95 C/W	3.09 C/W	1.93 C/W	1.56 C/W
910-40-1-15-2-B-0	15	40	9.51 C/W	2.77 C/W	1.73 C/W	1.37 C/W
910-40-1-19-2-B-0	18	40	9.06 C/W	2.74 C/W	1.52 C/W	1.17 C/W
910-40-1-21-2-B-0	21	40	8.62 C/W	2.22 C/W	1.35 C/W	.99 C/W
910-40-1-23-2-B-0	23	40	8.3 C/W	2.01C/W	1.19 C/W	.87 C/W
910-40-1-28-2-B-0	28	40	7.55 C/W	1.8 C/W	1.04 C/W	.75 C/W
910-40-1-33-2-B-0	33	40	6.78 C/W	1.61 C/W	.88 C/W	.64 C/W



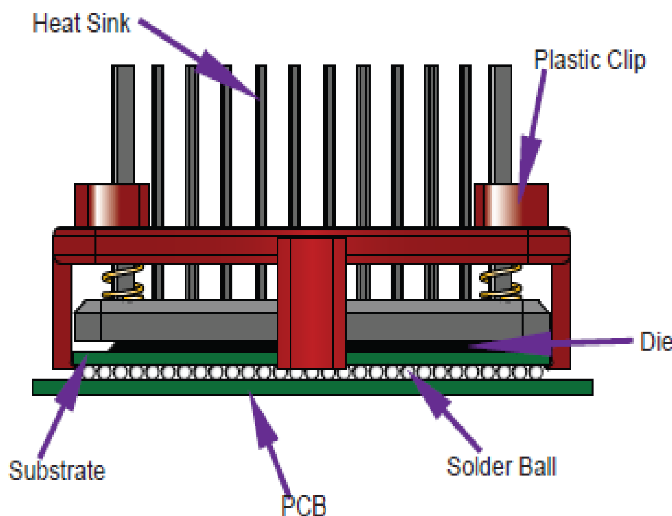


ASSEMBLY INSTRUCTION:

STEP 1: Center heat Sink onto BGA. Tilt and hook one side of the clip under the BGA chip.

STEP 2: Press down the other side of clip to snap it onto the BGA chip.

STEP 3: Make sure the stop pin is not on top of the chip set. Installation is now complete.



Wakefield-Vette's heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.

SHOCK TEST SPECIFICATION :
Wave Form : Half sine wave
Acceleration : 50 g
Duration Time : 11 ms
No. of Shock : Each axis 3 times
Shock Direction : ±X, ±Y, ±Z axis
Reliability & Communication Testing Instruments

Random Vibration Test
Frequency : 5 Hz to 500 Hz
Acceleration : 3.13 grms
P.S.D : 0.01 g2/HZ (5 Hz)
0.02 g2/HZ (20 Hz to 500 Hz)
Test Axis : X, Y, Z axis
Test Time : 10 mins (Each axis)
Total Test Time : 30 mins